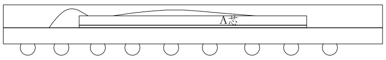
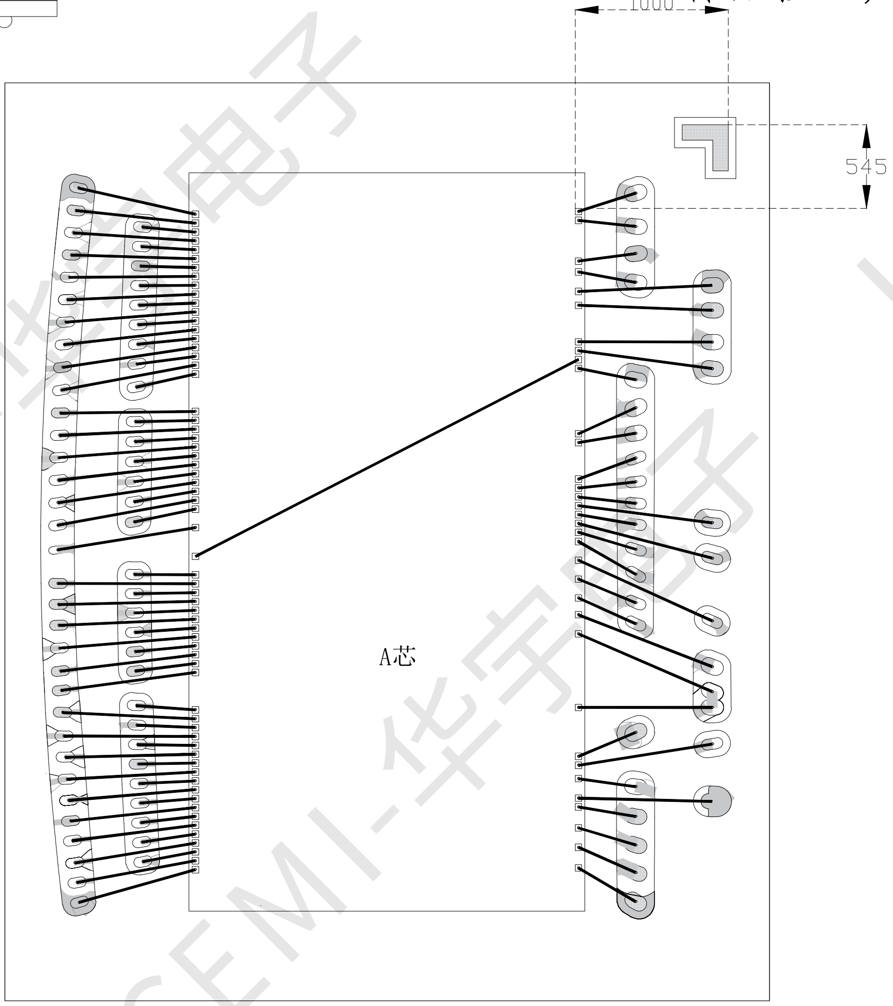
池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.	1152	线图号 Drawing No.	HY-PX-1152-002 A	页码 Page 1 / 4
	产品名称 Product Type	SD6001A	封装外型 PKG Type	WBBGA100B(5×6×0.66-P0.45)	

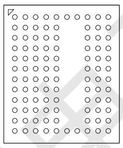
焊线种类 Wire Type	焊线直径(µm) Wire Diameter	焊线根数 NO. of wire	焊线总长(µm) Total wire length	最长线长(µm) Longest wire length	最短线长(µm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
金钯铜丝 AuPdCu	18um	97	82584	2815	350	首选(Preferred)：G311ACCver.GR 备选(Optional)：	WBBGA100B(050060)1152002
客户图号 Customer drawing NO.							



样品验证，禁止量产！

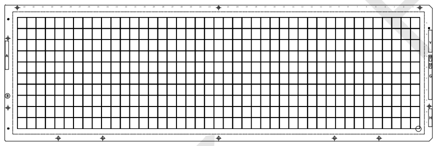


封装类型	WB-BGA
塑封厚度	300um
锡球型号/尺寸/间距	SAC305 /200um/450um
基板切割道	250um
基板厚度	210um
表面处理	TOP & BOTTOM:NiAu



底部示意图

框架传送方向（装片）：
L/F Direction（D/A）：三圆孔朝上



实物图：
Chip photo：

特殊说明 Special Instructions：

注意：

说明 Instructions	粘片胶类型 epoxy type	芯片名称 Die name	晶圆材质 Wafer material	芯片尺寸（不含切割道） Die Size (without scribe line)	最小焊盘尺寸 Min BPO (µm²)	最小焊盘间距 Min BPP(µm)	铝垫厚度 (µm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Street line (µm) *	晶圆尺寸Wafer Size	是否激光切割 If laser ?	减薄厚度 (µm) Wafer Thickness
A芯：DIE A	导电胶 (conductivity) 2100A	SD6001A	Si	4825um*2590um	43um *43um	15	1	有	60um	12寸	否	120

拟制 Prepared by		制图日期 Create Date	2025/11/21	生效日期 Effective Date		客户确认签字/盖章： Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

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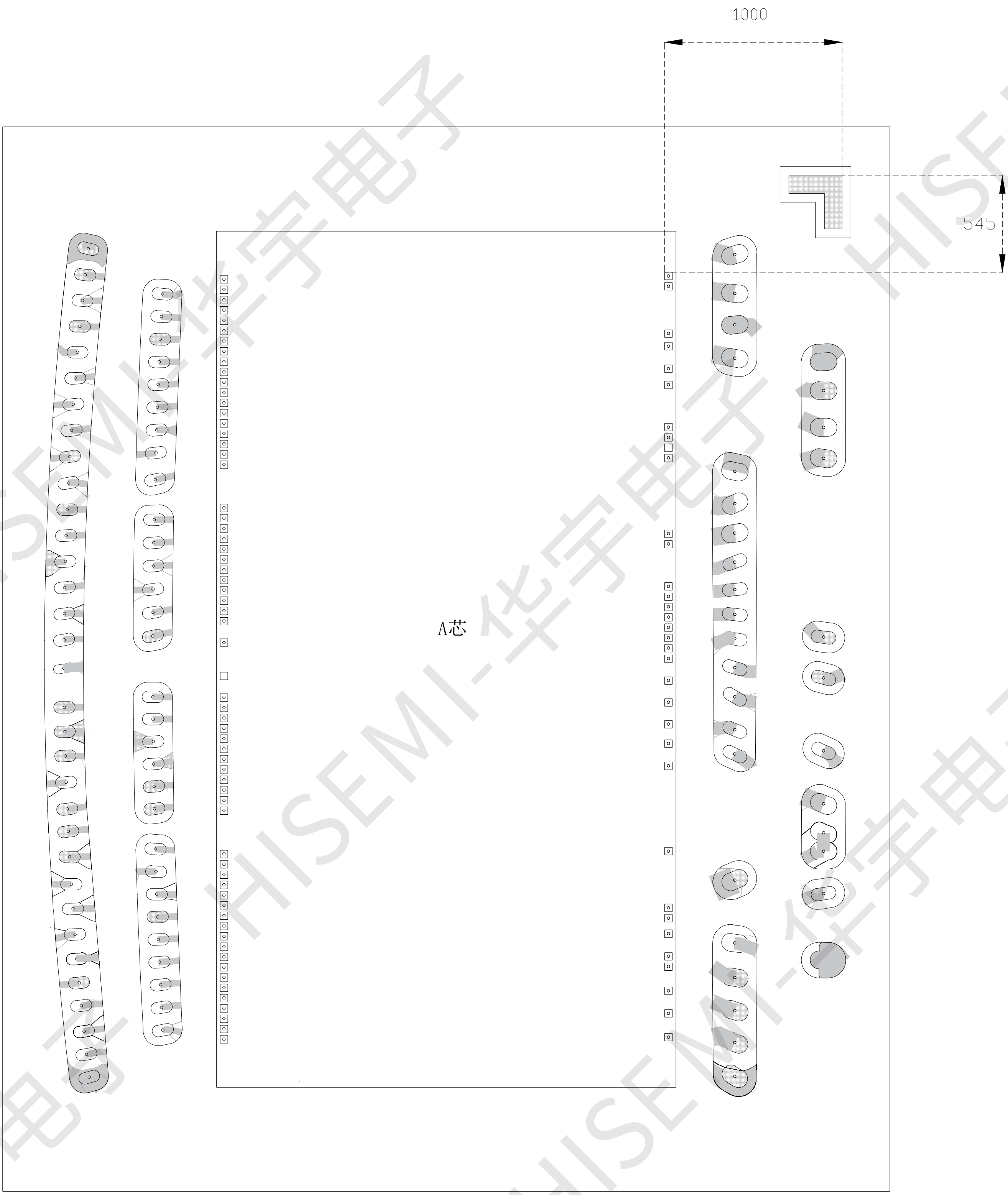
	产品名称 Product Type	SD6001A	封装外型 PKG Type	WBBGA100B(5×6×0.66-P0.45)	

装片示意：

比例：1.5：1

样品验证，禁止量产！



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18 um金钯铜丝键合示意:
32根线

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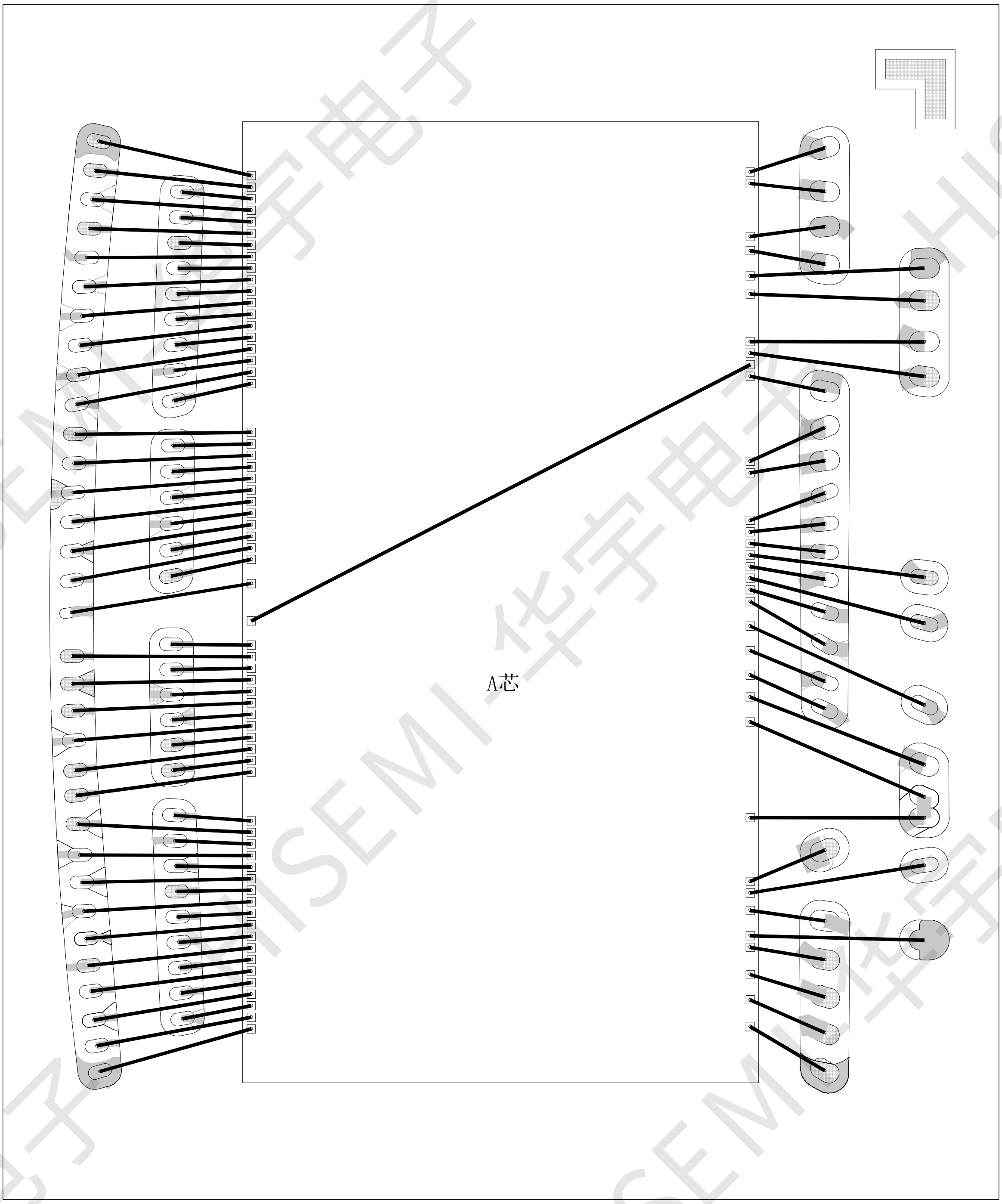

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焊线图纸 Bonding Diagram	产品名称 Product Type	SD6001A	封装外型 PKG Type	WBBGA100B(5×6×0.66-P0.45)	

叠构示意：

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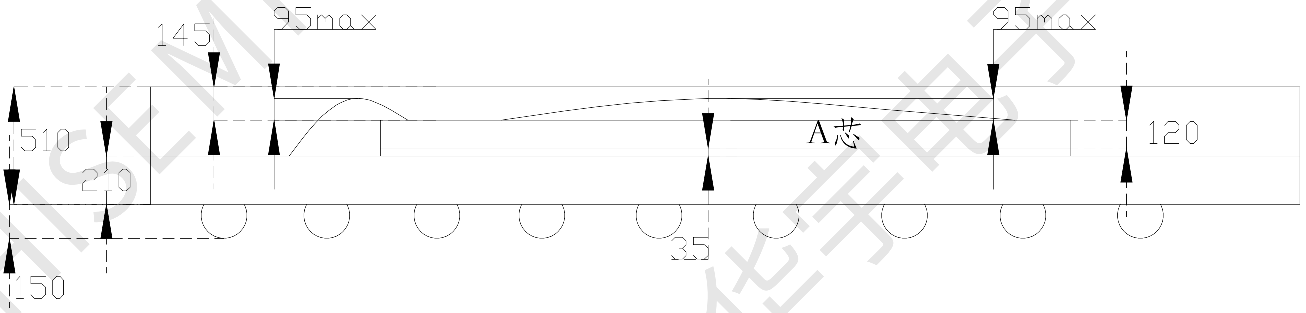

履历		
序号	内容	日期
1	新发行	2025.10.22
2	更新打线分布	2025.11.21

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